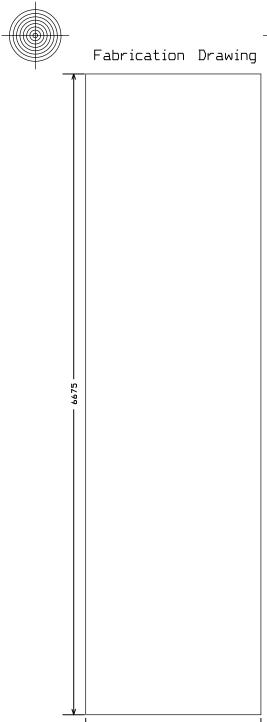
## BPM TGF Daughter Card Rev 1.1, Oct 18 2004



- 1825



SMT Pad Count: Layer Stackup:

Top: 0 1) Component Side 2) Power Plane 3) Ground Plane 4) Solder Side Bottom: 24

ThruHole Count:82

## Job Spec's

Material: FR-4

Material Thickness: 0.063"

Copper Weight: 1/2oz Inner/Outer Layers

Finnish/Plating: Tin-Lead SolderMask Type: LPI

SilkScreen Layers: Top & Bottom

Min. Trace Width: 6mil Min. Trace Spacing: 6mil Smallest Hole Size: 12mil Largest Hole Size: 120mil

Job Turn Around Time: 10 Day Turn

Job Qnt.: 38 Pieces

## Controled Impedence:

All Bot Layer 10mil traces are to be 50 ohms to Top layer GND plane. 6mil distance between solder side and ground plane.

